#### **ABSOLUTE MAXIMUM RATINGS**

PVDD to PGND	0.3V to +30V
	0.3V to +0.3V
IN, PRE, PC, COM to AGND	0.3V to (V <sub>REG</sub> + 0.3V)
MUTE, SHDN to AGND	0.3V to +6V
REG to AGND	0.3V to (V <sub>S</sub> + 0.3V)
Vs to AGND	0.3V to +6V
OUT+, OUT- to PGND	0.3V to $(PVDD + 0.3V)$
C1N to PGND	0.3V to (PVDD + 0.3V)
C1P to PGND(	PVDD - 0.3V) to (V <sub>CHOLD</sub> + 0.3V)
CHOLD to PGND	(V <sub>C1P</sub> - 0.3V) to +36V
OUT+, OUT-, Short Circuit to P	GND or PVDDContinuous
Thermal Limits (Notes 1, 2)	
Continuous Power Dissipation	$(T_A = +70^{\circ}C)$
24-Pin TQFN Single-Layer P	CB (derate 20.8mW/°C
above +70°C)	1666.7mW
	48°C/W
θJC	3°C/W

Continuous Power Dissipation	
24-Pin TQFN Multiple-Layer PCB	
(derate 27.8mW/°C above +70°C	:)2222.2mW
hetaJA	36°C/W
θJC	3°C/W
Operating Temperature Range	40°C to +85°C
Storage Temperature Range	65°C to +150°C
Junction Temperature	+150°C
Lead Temperature (soldering, 10s)	+300°C

Note 1: Thermal performance of this device is highly dependent on PCB layout. See the *Applications Information* section for more detail.

Note 2: Package thermal resistances were obtained using the method described in JEDEC specification JESD51-7, using a four-layer board. For detailed information on package thermal considerations, refer to www.maxim-ic.com/thermal-tutorial.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

#### **ELECTRICAL CHARACTERISTICS**

 $(V_{PVDD}=12V, V_{AGND}=V_{PGND}=0, V_{\overline{SHDN}}=V_{\overline{MUTE}}=5V, C1=0.1\mu F, C_{IN}=0.47\mu F, C2=C_{COM}=C_{REG}=1\mu F, R_{IN}=R_{FB}=20k\Omega, R_{L}=\infty$ , AC measurement bandwidth 22Hz to 22kHz,  $T_{A}=T_{MIN}$  to  $T_{MAX}$ , unless otherwise noted. Typical values are at  $T_{A}=+25^{\circ}C$ .) (Note 3)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	
AMPLIFIER DC CHARACTERIS	rics .						
Speaker-Supply Voltage Range	PVDD	Inferred from PSRR test	8		28	V	
Undervoltage Lockout	UVLO			6.8		V	
Ovince ant County Course	1	$T_A = +25^{\circ}C$		15	20	Λ	
Quiescent Supply Current	IPVDD				25	mA	
Shutdown Supply Current	ISHDN	$V_{\overline{SHDN}} = 0$ , $T_A = +25^{\circ}C$		1	10	μΑ	
REG Voltage	V <sub>REG</sub>		4.0	4.2	4.5	V	
Preregulator Voltage	Vs			4.85		V	
COM Voltage	Vcom		1.94	2.06	2.16	V	
INPUT AMPLIFIER CHARACTER	RISTICS						
Capacitive Drive	CL	No sustained oscillation		30		pF	
Output Swing		Sinking ±1mA (Note 4)		2.05		V	
Open-Loop Gain	Avo			88		dB	
Input Offset Voltage	Vos	IN to COM		±2		mV	
Input Amplifier Slew Rate				2.5	•	V/µs	
Input Amplifier Unity-Gain Bandwidth			3.5			MHz	

### **ELECTRICAL CHARACTERISTICS (continued)**

 $(V_{PVDD}=12V, V_{AGND}=V_{PGND}=0, V_{\overline{SHDN}}=V_{\overline{MUTE}}=5V, C1=0.1\mu F, C_{IN}=0.47\mu F, C2=C_{COM}=C_{REG}=1\mu F, R_{IN}=R_{FB}=20k\Omega, R_L=\infty, AC$  measurement bandwidth 22Hz to 22kHz,  $T_A=T_{MIN}$  to  $T_{MAX}$ , unless otherwise noted. Typical values are at  $T_A=+25^{\circ}C$ .) (Note 3)

PARAMETER	SYMBOL	CONDI	MIN	TYP	MAX	UNITS	
OUTPUT AMPLIFIER CHARACTE	RISTICS						
Output Amplifier Gain	Ay	Preamplifier gain = 0dl	13.1	13.6	14.1	dB	
Output Current Limit			3	4.6		А	
Output Offset	Vos	OUT+ to OUT-, $T_A = +$		±2	±10	mV	
Dower Cumply Dejection Datio	PSRR	$V_{PVDD} = 8V \text{ to } 28V, T_A$	= +25°C	65	80		dB
Power-Supply Rejection Ratio	ronn	$f = 1kHz$ , $100mV_{P-P}$ rip	ple		88		иь
Output Power	Dour	THD+N = 10%, R <sub>L</sub> = 8	Ω (Note 5)	6	7.4		W
Output Power	Pout	THD+N = 10%, R <sub>L</sub> = 4	Ω (Note 6)		13		] vv
THD + Noise	THD+N	$P_{OUT} = 2W, f = 1kHz, I$	$R_L = 8\Omega \text{ (Note 5)}$		0.06		%
Signal-to-Noise Ratio	SNR	A-weighted, P <sub>OUT</sub> = THD+N at 1%, f <sub>IN</sub> = 1kHz			97		dB
Noise	VN	A-weighted (Note 4)		100		μV <sub>RMS</sub>	
Efficiency	η	Pout = 4W			85		%
	K <sub>CP</sub>	Peak voltage, 32	Into shutdown		38		
Click and Dan Lavel		samples/second, A-weighted (Notes 4, 5, 8)	Out of shutdown		38	dBV	
Click-and-Pop Level			Into mute		38		
			Out of mute		38		]
Switching Frequency				270	300	330	kHz
Spread-Spectrum Bandwidth					±4		kHz
Thermal-Shutdown Level					+160		°C
Thermal-Shutdown Hysteresis					30		°C
Turn-On Time	ton	From shutdown to full of	peration		9	10	ms
DIGITAL INTERFACE (SHDN, MU	ITE)						
Input-Voltage High	V <sub>INH</sub>			2			V
Input-Voltage Low	V <sub>INL</sub>					0.8	V
Input-Voltage Hysteresis					50		mV
Input Leakage Current		T <sub>A</sub> = +25°C				±10	μΑ

Note 3: All devices are 100% production tested at  $T_A = +25$ °C, and all temperature limits are guaranteed by design.

Note 4: Amplifier inputs AC-coupled to GND.

Note 5:  $8\Omega$  resistive load in series with 68mH inductive load connected across OUT+ and OUT- outputs.

Note 6: 4Ω resistive load in series with 33μH inductive load connected across OUT+ and OUT- outputs for V<sub>PVDD</sub> ≤ 12V.

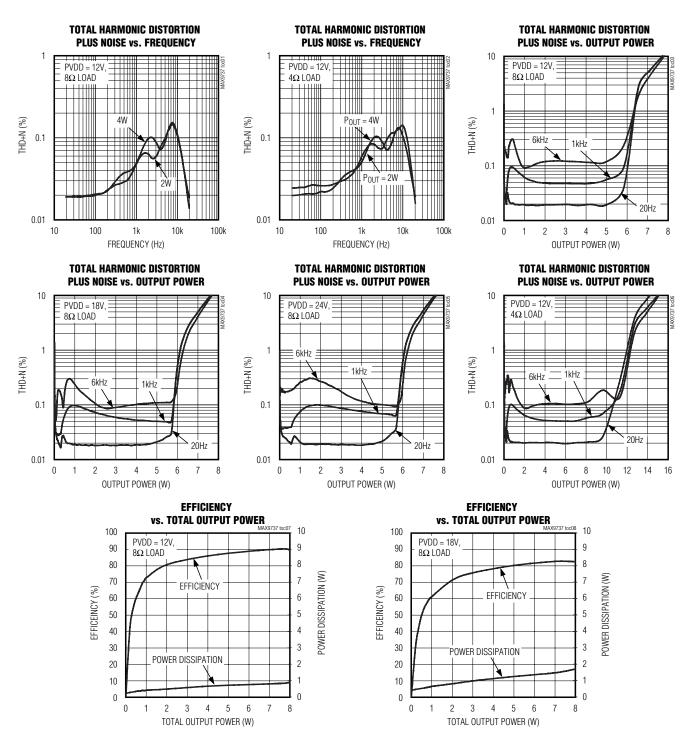
Note 7: Output amplifier gain is defined as:

$$20 \times log \left( \frac{I(V_{OUT+}) - (V_{OUT-})I}{IV_{PRE}I} \right)$$

Note 8: Mode transition controlled by SHDN and MUTE.

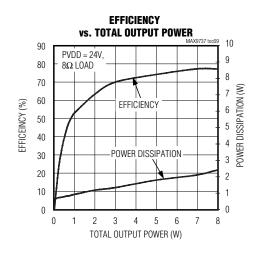
### Typical Operating Characteristics

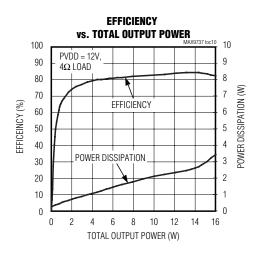
 $(V_{PVDD} = 12V, V_{GND} = V_{PGND} = 0, V_{\overline{SHDN}} = V_{\overline{MUTE}} = 5V, R_{IN} = R_{FB} = 20k\Omega$ , unless otherwise noted.)

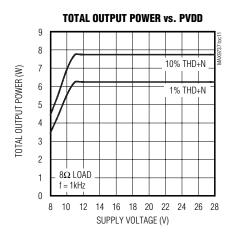


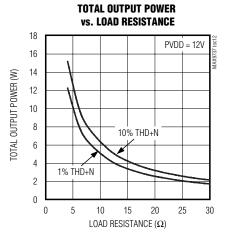
### Typical Operating Characteristics (continued)

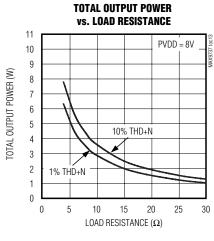
 $(V_{PVDD} = 12V, V_{GND} = V_{PGND} = 0, V_{\overline{SHDN}} = V_{\overline{MUTE}} = 5V, R_{IN} = R_{FB} = 20k\Omega$ , unless otherwise noted.)

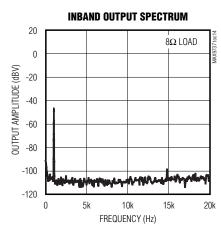


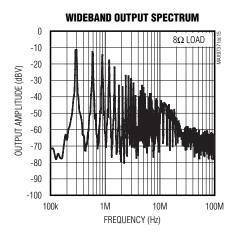


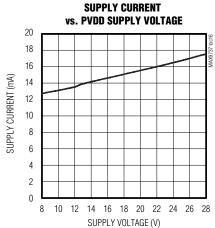






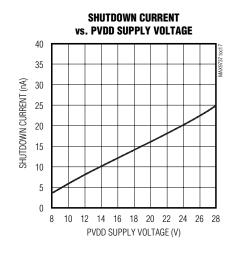


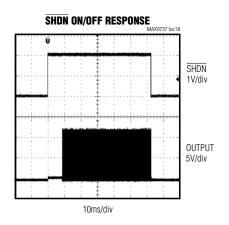


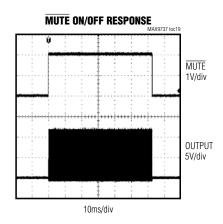


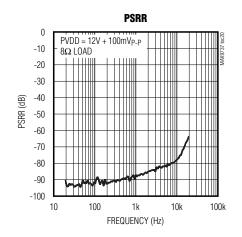
## Typical Operating Characteristics (continued)

 $(V_{PVDD} = 12V, V_{GND} = V_{PGND} = 0, V_{\overline{SHDN}} = V_{\overline{MUTE}} = 5V, R_{IN} = R_{FB} = 20k\Omega$ , unless otherwise noted.)









### **Pin Description**

PIN	NAME	FUNCTION
1, 17, 18	PVDD	Power Supply. Bypass PVDD to PGND with a 1µF capacitor connected to pin 1 and a 1µF capacitor connected to pins 17 and 18.
2	CHOLD	Charge-Pump Output. Connect a 1µF capacitor to PVDD.
3, 10, 11	AGND	Analog Ground
4	MUTE	Mute Input. Drive MUTE low to place the device in mute mode.
5	SHDN	Shutdown Input. Drive SHDN low to place the part in shutdown mode.
6	PC	Input Capacitor Precharge Connection. Connect between input resistor, R <sub>IN</sub> , and input coupling capacitor, C <sub>IN</sub> .
7	IN	Op Amp Inverting Input.
8	PRE	Op Amp Output. PRE is the output of the input operational amplifier.
9	COM	Internal 2.0V Bias. Bypass COM to AGND with a 1µF capacitor.
12	REG	Internal 4.2V Bias. Bypass REG to AGND with a 1µF capacitor.
13, 14	Vs	Internal 5.0V Bias. Bypass V <sub>S</sub> to AGND with a 1µF capacitor.
15	C1N	Charge-Pump, Flying-Capacitor Negative Terminal. Connect C1N to C1P through a 0.1µF capacitor.
16	C1P	Charge-Pump, Flying-Capacitor Positive Terminal. Connect C1P to C1N through a 0.1µF capacitor.
19, 20	OUT-	Negative Speaker Output
21, 22	PGND	Power Ground
23, 24	OUT+	Positive Speaker Output
_	EP	Exposed Pad. Must be externally connected to PGND.

### **Detailed Description**

The MAX9737 filterless, mono class D audio power amplifier offers Class AB audio performance and Class D efficiency with minimal board space. The device operates from an 8V to 28V supply range.

The MAX9737 features filterless, spread-spectrum modulation, externally set gain and a low-power shutdown mode that reduces supply current to less than 1µA. Comprehensive click-and-pop suppression and precharge circuitry reduce noise into and out of shutdown or mute within 10ms.

#### **Spread-Spectrum Modulation**

The MAX9737 features a unique spread-spectrum switching modulation that flattens EMI wideband spectral components, reducing radiated emissions from the speaker and cables. The switching frequency of the Class D amplifier varies randomly by ±4kHz around the 300kHz center frequency. Instead of a large amount of spectral energy present at multiples of the switching frequency, the energy is spread over a bandwidth that increases with frequency. Above a few MHz, the wideband spectrum looks like white noise for EMI purposes.

A proprietary amplifier topology ensures this white noise does not corrupt the noise floor in the audio bandwidth.

#### **Efficiency**

The high efficiency of a Class D amplifier is due to the output transistors acting as switches and therefore consume negligible power. Power loss associated with the Class D output stage is due to the MOSFET I<sup>2</sup>R losses, switching losses, and quiescent current.

Although the theoretical best efficiency of a linear amplifier is 78% at peak output power, under typical music reproduction levels, the efficiency falls to below 40%. The MAX9737 exhibits > 80% efficiency under the same conditions (Figure 1).

#### Shutdown

The MAX9737 features a shutdown mode that reduces power consumption to less than 1µA (typ), extending battery life in portable applications. Drive  $\overline{SHDN}$  low to place the device in low-power shutdown mode. In shutdown mode, the outputs are high impedance and the common-mode voltage at the output decays to zero.



#### **Mute Function**

The MAX9737 features a mute mode where the signal is attenuated at the speaker and the outputs stop switching. To mute the MAX9737, drive MUTE low.

#### **Click-and-Pop Suppression**

The MAX9737 features comprehensive click-and-pop suppression and precharge circuitry that reduce audible transients on startup and shutdown. The precharge circuit enables the amplifier within 10ms without any clicks or pops. Connect PC between the input resistor (R<sub>IN</sub>) and the input capacitor (C<sub>IN</sub>). For optimal click-and-pop suppression, use a  $0.47\mu F$  input coupling capacitor (C<sub>IN</sub>).

#### **Current Limit**

When output current exceeds the current limit, 4.6A (typ), the MAX9737 disables the outputs and initiates a 450µs startup sequence. The shutdown and startup sequence is repeated until the output fault is removed. Properly designed applications do not enter current-limit mode unless the output is short circuited or connected incorrectly.

#### **Thermal Shutdown**

When the die temperature exceeds the thermal-shut-down threshold, +160°C (typ), the MAX9737 outputs are disabled. When the die temperature decreases by 30°C, normal operation resumes. Some causes of thermal shutdown are excessively low load impedance, poor thermal contact between the MAX9737's exposed pad and the PCB, elevated ambient temperature, or poor PCB layout and assembly.

### \_Applications Information

#### Filterless Class D Operation

The MAX9737 meets EN55022B EMC radiation limits with an inexpensive ferrite bead and capacitor filter when the speaker leads are less than or equal to 1m (Figure 3). Select a ferrite bead with  $100\Omega$  to  $600\Omega$  impedance, and rated for 2A. The capacitor value varies based on the ferrite bead chosen and the speaker lead length. See Figure 2 for the correct connections of these components.

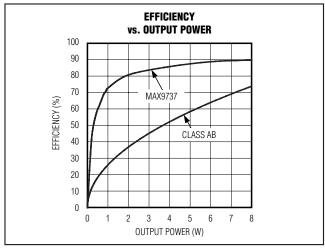


Figure 1. MAX9737 Efficiency vs. Class AB Efficiency

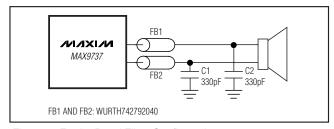


Figure 2. Ferrite Bead Filter Configuration

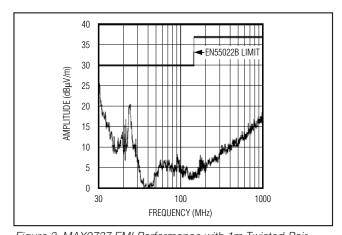


Figure 3. MAX9737 EMI Performance with 1m Twisted-Pair Speaker Cable

#### Table 1. Suggested Values for LC Filter

<b>R</b> <sub>L</sub> (Ω)	L1, L2 (μH)	C1 (µF)	C2, C3 (µF)	C4, C5 (μF)	R1, R2 (Ω)
4	10	0.47	0.10	0.22	10
8	15	0.15	0.15	0.15	15

3 \_\_\_\_\_\_*NIXI/*N

When evaluating the MAX9737 with a ferrite bead filter and resistive load, include a series inductor (68µH for  $8\Omega$  load and 33µH for  $4\Omega$  load) to model typical loud-speaker's behavior. Omitting the series inductor reduces the efficiency, the THD+N performance and the output power of the MAX9737. When evaluating with a loudspeaker, no series inductor is required.

#### **Inductor-Based Output Filters**

Some applications use the MAX9737 with a full inductor/capacitor-based (LC) output filter. See Figure 4 for the correct connections of these components.

The load impedance of the speaker determines the filter component selection (see Table 1).

Inductors L1 and L2 and capacitor C1 form the primary output filter. Capacitors C2 and C3 provide common-mode filtering to reduce radiated emissions. Capacitors C4 and C5, plus resistors R1 and R2, form a Zobel at the output. A Zobel corrects the output loading to compensate for the rising impedance of the loudspeaker. Without a Zobel, the filter exhibits peaking near the cutoff frequency.

### **Component Selection**

#### **Gain-Setting Resistors**

The output stage provides a fixed internal gain in addition to the externally set input stage gain. The fixed-output stage gain is set at 13.6dB (4.8V/V). Set overall gain by using resistors RF and RIN (Figure 5) as follows:

$$A_{V} = -4.8 \left( \frac{R_{F}}{R_{IN}} \right) V/V$$

where  $A_V$  is the desired voltage gain. Choose  $R_F$  between  $10k\Omega$  and  $50k\Omega.$ 

The PRE terminal is an operational amplifier output, allowing the MAX9737 to be configured as a filter or an equalizer.

### Input Capacitor

An input capacitor,  $C_{IN}$ , in conjunction with the input resistor,  $R_{IN}$ , of the MAX9737 forms a highpass filter that removes the DC bias from an incoming signal. The AC-coupling capacitor allows the amplifier to bias the signal to an optimum DC level. Assuming negligible source impedance, the -3dB point of the highpass filter is given by:

$$f_{-3dB} = \frac{1}{2\pi R_{IN} C_{IN}}$$

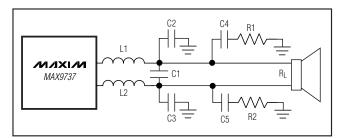


Figure 4. LC Filter Configuration

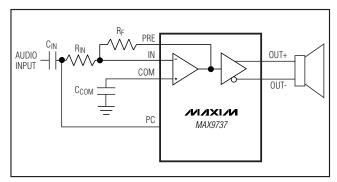


Figure 5. Preamplifier Gain Configuration

Choose  $C_{IN}$  such that  $f_{-3dB}$  is well below the lowest frequency of interest. To reduce low-frequency distortion, use capacitors whose dielectrics have low-voltage coefficients. Capacitors with high-voltage coefficients cause increased distortion close to  $f_{-3dB}$ . For best click-and-pop suppression, use a  $0.47\mu F$  input capacitor.

#### **COM Capacitor**

COM is the output of the internally generated DC bias voltage. Bypass COM with a 1µF capacitor to AGND.

#### Regulator Capacitor

REG is the output of the internally generated DC bias voltage. Bypass REG with a 1µF capacitor to AGND.

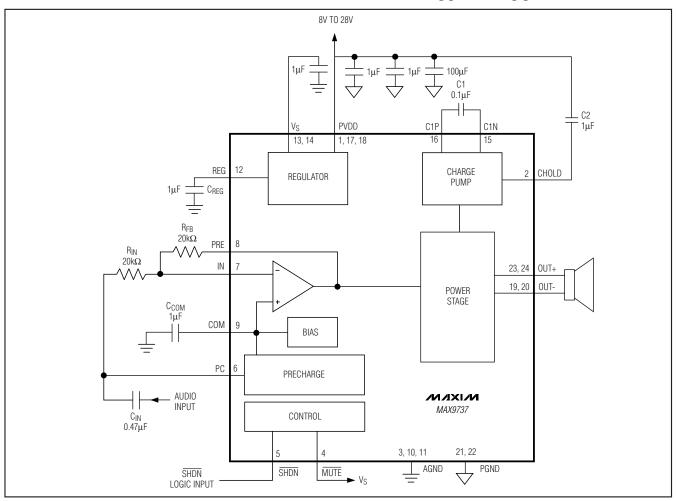
#### **Power Supplies**

The MAX9737 features separate supplies for signal and power portions of the device, allowing for the optimum combination of headroom, power dissipation and noise immunity. The speaker amplifiers are powered from PVDD and can range from 8V to 28V. The remainder of the device is powered by an internal 5V regulator, Vs.

#### Internal Regulator

The MAX9737 features an internal 5V regulator, Vs, powered from PVDD. Bypass Vs with a 1 $\mu$ F capacitor to AGND.

### **Typical Application Circuit**



#### Supply Bypassing, Layout, and Grounding

Proper layout and grounding are essential for optimum performance. Use wide traces for the power-supply inputs and amplifier outputs to minimize losses due to parasitic trace resistance. Proper grounding improves audio performance, minimizes crosstalk between channels, and prevents switching noise from coupling into the audio signal. Connect PGND and AGND together at a single point on the PCB. Route all traces that carry switching transients away from AGND and the traces/components in the audio signal path.

Bypass PVDD with two 1 $\mu$ F capacitors to PGND. Place the bypass capacitors as close as possible to the MAX9737. Place a 100 $\mu$ F capacitor between PVDD and PGND. Bypass Vs, VCOM, and VREG with a 1 $\mu$ F capacitor to AGND.

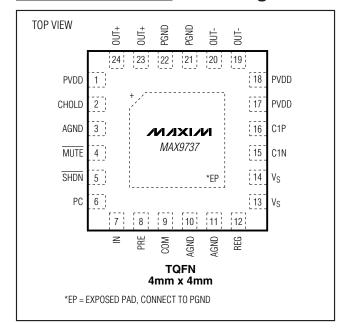
Use wide, low-resistance output traces. Current drawn from the outputs increases as load impedance decreases. High-output trace resistance decreases the power delivered to the load. The MAX9737 TQFN package features an exposed thermal pad on its underside. This pad lowers the package's thermal resistance by providing a heat conduction path from the die to the PCB. Connect the exposed thermal pad to PGND by using a large pad and multiple vias to the PGND plane.

10 \_\_\_\_\_\_/N/XI/M

## **Pin Configuration**

\_\_\_\_\_Chip Information

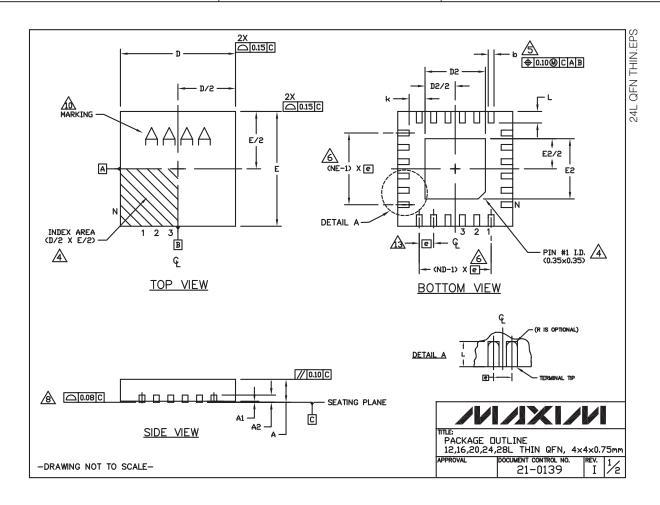
PROCESS: BiCMOS



### **Package Information**

For the latest package outline information and land patterns, go to www.maxim-ic.com/packages

PACKAGE TYPE	PACKAGE CODE	DOCUMENT NO.
24 TQFN-EP	T244+4	<u>21-0139</u>



### Package Information (continued)

For the latest package outline information and land patterns, go to www.maxim-ic.com/packages.

					COM	4MDN	DIM	IENS	ZNDI						
PKG 12L 4×4		16	16L 4×4			20L 4×4		24L 4×4			28L 4×4				
REF.	MIN.	NDM.	MAX.	MIN.	NOM.	MAX.	MIN.	NDM.	MAX.	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
Α	0.70	0.75	0.80	0.70	0.75	0.80	0.70	0.75	0.80	0.70	0.75	0.80	0.70	0.75	0.80
A1	0.0	0.02	0.05	0.0	0.02	0.05	0.0	20.0	0.05	0.0	0.02	0.05	0.0	0.02	0.05
A2	A2 0.20 REF		0	0.20 REF		0.20 REF		0.20 REF			0.20 REF				
b	0.25	0.30	0.35	0.25	0.30	0.35	0.20	0.25	0.30	0.18	0.23	0.30	0.15	0.20	0.25
D	3.90	4.00	4.10	3.90	4.00	4.10	3.90	4.00	4.10	3.90	4.00	4.10	3.90	4.00	4.10
Ε	3.90	4.00	4.10	3.90	4.00	4.10	3.90	4.00	4.10	3.90	4.00	4.10	3.90	4.00	4.10
e	(	.80 BS	C.	0.65 BSC.		0.50 BSC.		0.50 BSC.			0.40 BSC.				
k	0.25	-	ı	0.25	-	-	0.25	-	ı	0.25	-	ı	0.25	-	ı
L	0.45	0.55	0.65	0.45	0.55	0.65	0.45	0.55	0.65	0.30	0.40	0.50	0.30	0.40	0.50
N	N 12 16			20		24			28						
ND	3			4			5			6			7		
NE	3				4		5		6			7			
Jedec Var.	ec VGGB			WGGC		,	WGGD-:	1		WGGD-	2		WGGE		

EXPOSED PAD VARIATIONS									
PKG.		D2			E2				
CODES	MIN.	N□M.	MAX.	MIN.	NDM.	MAX.			
T1244-3	1.95	2.10	2.25	1.95	2.10	2.25			
T1244-4	1.95	2.10	2.25	1.95	2.10	2.25			
T1644-3	1.95	2.10	2.25	1.95	2.10	2.25			
T1644-4	1.95	2.10	2.25	1.95	2.10	2.25			
T2044-2	1.95	2.10	2.25	1.95	2.10	2.25			
T2044-3	1.95	2.10	2.25	1.95	2.10	2.25			
T2444-2	1.95	2.10	2.25	1.95	2.10	2.25			
T2444-3	2.45	2.60	2.63	2.45	2.60	2.63			
T2444-4	2.45	2.60	2.63	2.45	2.60	2.63			
T2444N-4	2.45	2.60	2.63	2.45	2.60	2.63			
T2444M-1	2.45	2.60	2.63	2.45	2.60	2.63			
T2844-1	2.50	2.60	2.70	2.50	2.60	2.70			

#### NOTES

- 1. DIMENSIONING & TOLERANCING CONFORM TO ASME Y14.5M-1994.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS. ANGLES ARE IN DEGREES.
- N IS THE TOTAL NUMBER OF TERMINALS.
- ⚠ THE TERMINAL #1 IDENTIFIER AND TERMINAL NUMBERING CONVENTION SHALL CONFORM TO JESD 95-1 SPP-012. DETAILS OF TERMINAL #1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE TERMINAL #1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE.
- DIMENSION 6 APPLIES TO METALLIZED TERMINAL AND IS MEASURED BETWEEN 0.25mm AND 0.30mm FROM TERMINAL TIP.

  ND AND NE REFER TO THE NUMBER OF TERMINALS ON EACH D AND E SIDE RESPECTIVELY.
- DEPOPULATION IS POSSIBLE IN A SYMMETRICAL FASHION.
- 7. DEPUPULATION IS POSSIBLE IN A SYMMETRICAL FASHION.

  © COPLANARITY APPLIES TO THE EXPOSED HEAT SINK SLUG AS WELL AS THE TERMINALS.
- DRAWING CONFORMS TO JEDEC MO220, EXCEPT FOR T2444-3, T2444-4 AND T2844-1.
- 9. DRAWING CUNFLIRMS IN JEDEC MUSES, EACET FOR LETTY

  MARKING IS FOR PACKAGE ORIENTATION REFERENCE ONLY.
- 11. COPLANARITY SHALL NOT EXCEED 0.08mm
- WARPAGE SHALL NOT EXCEED 0.10mm.
- ⚠ LEAD CENTERLINES TO BE AT TRUE POSITION AS DEFINED BY BASIC DIMENSION 'e', ±0.05.

  14. NUMBER OF LEADS SHOWN ARE FOR REFERENCE ONLY.
- 15. ALL DIMENSIONS ARE THE SAME FOR LEADED (-) & PhFREE (+) PACKAGE CODES.

PACKAGE DUTLINE 12,16,20,24,28L THIN QFN, 4×4×0.75mm 21-0139

-DRAWING NOT TO SCALE-

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